

ATX-M-CC462-T6

Micro-ATX COM Express® Type 6 Carrier Board

MADE IN USA

Features

Industrial Carrier Board

- Supports all interfaces on the WINSYSTEMS COMeT6 Modules
- Form Factor: Micro-ATX
 9.6 x 9.6 inches (243.84 x 243.84 mm)
- -40°C to +85°C with supporting cooling options
- Made in the USA
- ATX Mode: Standard ATX Power input
- AT Mode: 12VDC +/- 5%

Display and Graphics

- 3x DisplayPort++ Ports
- Support for Dual Channel LVDS and eDP, including backlight

Network

1x RJ45 supporting 2.5Gbps Ethernet from COMe

Connectivity and I/O

- 4x USB 3.2 Gen1 (2x Front Panel Type A, 2x Header)
- 4x USB 2.0 (2x Front Panel, 2x Header)
- PCI Express Expansion
 - 1x PCI Express Gen4 x16
 - 2x PCI Express Gen3 x4
- Serial UART
 - 2x RS 232 2pin (Tx/Rx) from COMe Module
 - 2x RS232/422/485 Multiprotocol Legacy mode

Storage/SATA Channels

• 4x SATA Type III (6Gbps) channels

Software

Windows 10, Linux

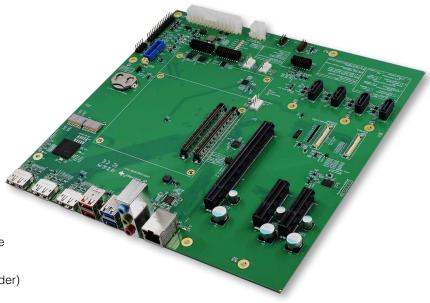
Product Description

The ATX-M-CC462-T6 is a fully featured COM Express Type 6 carrier board designed to use industry standard COM Express Type 6 modules including the WINSYSTEMS COMeT6-TGLU Series of COM Express Type 6 modules featuring the Intel® Tiger Lake UP3 SOC.

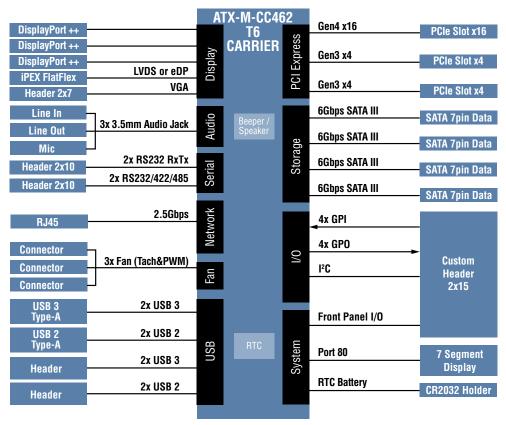
The carrier implements the full capabilities of the Type 6 connectors and is compliant with PICMG® COM Express Rev 3.0 Specifications. The ATX-M-CC462-T6 carrier board has multiple interface options including 3x PCIe slots, multiple Video options, 4x SATA devices, 8x USB ports (2 and 3), and high speed 2.5Gbps Ethernet that make it highly configurable for use in any application.

This is a production-ready reference board which can be taken directly into production for customer use, or available schematics and layout can be leveraged for customers working to design their own carrier.

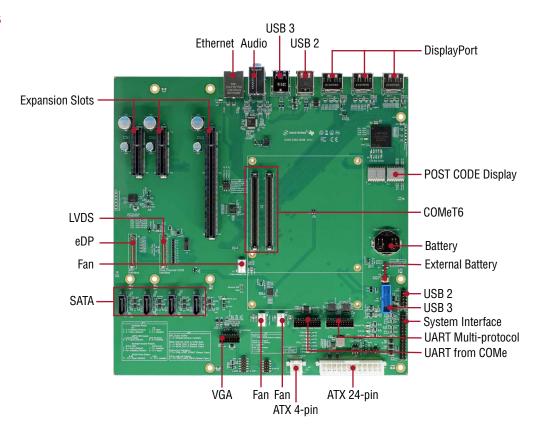
The carrier board is designed to support a wide range of commercial, industrial, and automotive applications across a wide temperature spectrum (-40°C to +85°C).



Block Diagram



Connectors



Technical Specifications

FORM FACTOR	Micro-ATX 9.6 x 9.6 inches (244 x 244mm)			
STORAGE	4x SATA Type III (6Gb/s) channels			
DISPLAY	Quad Simultaneous Displays 3x DisplayPort++ Support for Dual Channel LVDS and eDP including backlight VGA			
NETWORK INTERFACE	1x 2.5Gbps Ethernet			
ONBOARD I/O	 4x USB 3 (2x Front Panel Type A, 2x Header) 4x USB 2 (2x Front Panel Type A, 2x Header) 2x RS-232 2pin (Tx/Rx) from COMe Module 2x RS-232/422/485 Multiprotocol Legacy mode 1x PCle Gen4 x16 slot 2x PCle Gen3 x4 slot 1x EEPROM socket 1x LPC header 3x Fan Header 1x GPIO/Feature connector 			
FRONT PANEL CONNECTORS	 1x 2.5 Gbps Ethernet RJ45 port 1x Audio with separate 3.5mm jacks for MIC, LINE-OUT, LINE-IN 3x Standard DisplayPort connectors 2x USB 3 Type A connector 2x USB 2 Type A connector 			
POWER	ATX Mode: Standard ATX Power input AT Mode: 12VDC +/- 5%			
ENVIRONMENTAL	Operating Temperature Storage Temperature Thermal Shock Shock IAW IEC60068-2-27 Vibration IAW IEC60068-2-27 CE Compliant CISPR A and FCC Class A ESD (Human body) – JEDEC Standard JA114/JS-001 OCCUPATION IAW IEC60068-2-27 CE Compliant CISPR A and FCC Class A ESD (Human body) – JEDEC Standard JA114/JS-001			
MECHANICAL	Dimensions: 9.6 in x 9.6 in (mITX) (243.84 mm x 243.84 mm) Weight: 8.0 oz (225 gm) without COMe Module PC Board thickness: 0.078 inches (2.0 mm)			

Order Information

CARRIER BOARD PART NUMBER	ATX-M-CC462-T6			
COM EXPRESS Type 6 reference Modules	COMET6-1185GRE-32IL COMET6-1145GRE-16IL COMET6-1115GRE-8IL	Intel Core-i7,32GB LPDDR4,LVDS,VPRO, INDUSTRIAL TEMP Intel Core-i5,16GB LPDDR4, LVDS,VPRO, INDUSTRIAL TEMP Intel Core-i3,16GB LPDDR4, LVDS, INDUSTRIAL TEMP		
CABLES AND ACCESSORIES	CBL-SET-462-1	Cable Set includes: 1X DisplayPort 1X VGA 1X SATA 2X COM/SERIAL 1X USB3 (Dual) 1X USB2 (Dual) 1x RJ45 Patch Cable	TCBL-DP-6A CBL-234-G-1-1.375B CBL-SATA-701-20 CBL-SER2-202-12A CBL-USB2-U03-08A CBL-USB2-U12-11A CBL-ENET-060A	

Expansion and Customization Options

WINSYSTEMS provides customization options for OEMs with minimum order quantities. Please contact an Application Engineer for details. Additional cables, expansion cards, power supplies, and solid-state drives to complete your embedded computing solution including data acquisition, communications, location, and other features are available. Our Application Engineers are available to guide you through product selection and customized options.

NOW ACCEPTING RFQs FOR DELIVERY IN Q3 | 2023

Contact us for more information about this new product.

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Contact an Application Engineer or visit our website for more information.



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